WHAT IS CLAIMED IS:

1. An apparatus comprising:

one or more leads for a component to be inserted into an opening of a substrate, the one or more leads to substantially prevent movement of the component perpendicular to substrate.

2. An apparatus according to Claim 1, wherein the component is an electronic component and the substrate is a printed circuit board.

3. An apparatus comprising:

an electronic component body; and

one or more leads coupled to and extending from the electronic component body,

wherein a first lead of the one or more leads comprises a first portion in contact with the body, a second portion comprising an end of the first lead, and a third portion between the first portion and the second portion,

wherein a portion of the first portion is to reside in an opening of a substrate,

wherein a portion of the third portion is to contact a first side of the substrate, and

wherein a portion of the second portion is to reside in the opening.

4. An apparatus according to Claim 3, wherein a second portion of the second portion is to contact a second side of the substrate.

5. An apparatus according to Claim 4, wherein the electronic component body is to be disposed away from the substrate.

6. An apparatus according to Claim 3, wherein the electronic component body is to contact a second side of the substrate.

7. A system comprising:

an electronic component body;

one or more leads coupled to and extending from the electronic component body; and

a substrate defining at least one opening,

wherein a first lead of the one or more leads comprises a first portion in contact with the body, a second portion comprising an end of the first lead, and a third portion between the first portion and the second portion,

wherein a portion of the first portion resides in the opening,

wherein a portion of the third portion contacts a first side of the substrate, and

wherein a portion of the second portion resides in the opening.

8. A system according to Claim 7, wherein a second portion of the second portion contacts a second side of the substrate.

9. An system according to Claim 8, wherein the electronic component body is disposed away from the substrate.

10. An system according to Claim 7, wherein the electronic component body contacts a second side of the substrate.

11. An apparatus comprising:

an electronic component body; and

one or more leads coupled to and extending from the electronic component body,

wherein a first lead of the one or more leads comprises a first leg and a second leg, the first leg and the second leg defining an acute angle therebetween.

12. An apparatus according to Claim 11,

the second leg comprising a first portion defining the acute angle with the first leg, and a second portion substantially parallel to the first leg.

13. An apparatus according to Claim 12,

the second leg comprising a third portion defining an obtuse angle with the second portion.

14. An apparatus according to Claim 13,

wherein a length of the second portion is substantially equal to a thickness of a substrate to which the electronic component body is to be mounted.

15. A method comprising:

bending an electronic component body lead to form a first leg and a second leg, the first leg and the second leg defining an acute angle therebetween.

16. A method according to Claim 15, further comprising:

bending the second leg to form a first portion defining the acute angle with the first leg, and a second portion substantially parallel to the first leg.

17. A method according to Claim 16, further comprising

bending the second leg to form a third portion defining an obtuse angle with the second portion.

18. A method according to Claim 17,

wherein a length of the second portion is substantially equal to a thickness of a substrate to which the electronic component body is to be mounted.

19. A method according to Claim 15, further comprising:

electrically coupling the lead to an electronic component body.

20. A method according to Claim 15, wherein the lead is attached to an electronic component body.

21. A method comprising:

placing a lead of an electronic component body into an opening of a substrate, wherein the lead comprises a first leg and a second leg defining an acute angle therebetween.

22. A method according to Claim 21, the second leg comprising a first portion defining the acute angle with the first leg, and a second portion substantially parallel to the first leg.

23. A method according to Claim 22, the second leg comprising a third portion defining an obtuse angle with the second portion.

24. A method according to Claim 23,

wherein a length of the second portion is substantially equal to a thickness of the substrate.

25. A method according to Claim 21, further comprising:

electrically coupling the lead to the substrate.

26. An expansion card comprising:

a circuit board;

a connector coupled to the circuit board, the connector to connect to a motherboard; and

an electronic component body coupled to the circuit board, the electronic component body comprising one or more leads coupled to and extending from the electronic component body,

wherein a first lead of the one or more leads comprises a first leg and a second leg, the first leg and the second leg defining an acute angle therebetween.

27. An expansion card according to Claim 26,

the second leg comprising a first portion defining the acute angle with the first leg, and a second portion substantially parallel to the first leg.

28. An expansion card according to Claim 27,

the second leg comprising a third portion defining an obtuse angle with the second portion.

29. An expansion card according to Claim 28,

wherein a length of the second portion is substantially equal to a thickness of the circuit board.